Design and Chip Implementation of a Heterogeneous Multi-core DSP

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Trend of System-on-Chips (SoCs)



Evolution of processor chips

YHFT-QDSP: a heterogeneous multi-core Digital Signal Processor



A RISC CPU core □Four enhanced **YHFT-DSP/700 cores D**several peripherals **Dindividual memory** interfaces **Three kinds of communication** •AHB/MB Bridge Fast Shared Data **Pool (FSDP)** • Qlink-Crossbar-**PCIE** mechanism

Chip Implementation of YHFT-DSP



micrograph of YHFT-QDSP

Chip Implementation of YHFT-DSP

◀──── 10.70mm ─── ► ◀── 4.19m		im	
DSP DSP Core-1 DSP Core-2			
	Characteristics of the YHFT-QDSP		
	Technology	SMIC 130nm LV	T CMOS,
		1 Poly, 8 Metals	(Cu)
	Transistors	73.9 million	(YHFT-QDSP)
		17.1 million	(DSP core)
		0.82 million	(CPU core)
	Die Area	114.49 mm^2	(YHFT-QDSP)
		19.32 mm^2	(DSP core)
		1.29 mm^2	(CPU core)
	Clock Frequency	350MHz@1.2V	(DSP core)
		$200 \overline{MHz@1.2V}$	(CPU core)
	Power Dissipation	2.99W@1.2V	(YHFT-QDSP)

Performance Evaluation of YHFT-DSP

2D FFT benchmark



When the data size is relatively small, e.g. 32x32 points, data transfer by the FSDP is faster than by the QLink.
As the data size is larger, data transfer by the QLink is faster.
As we can see, using the FSDP and the Qlink together obtains the best speedups.